



AZ2117

Description

The AZ2117 is a low dropout three-terminal regulator.

The AZ2117 has been optimized for low voltage where transient response and minimum input voltage are critical. It provides current limit and thermal shutdown. Its circuit includes a trimmed bandgap reference to assure output voltage accuracy to be within $\pm 1\%$. On-chip thermal shutdown provides protection against a combination of high current and ambient temperature that would create excessive junction temperature.

The AZ2117 is available in ADJ output voltage version. It is available in an adjustable version which can set the output voltage with two external resistors.

The AZ2117 is available in the industry-standard SOT223 Series power packages.

Features

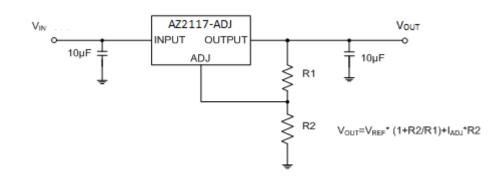
- Current Limit: 1.35A (Typ)
- Output Noise from 10Hz to 10kHz: 0.003% of V_{OUT}
- PSRR at I_{OUT} = 300mA and f = 120Hz: 60dB
- Output Voltage Accuracy: ±1%
- On-chip Thermal Shutdown
- Maximum Quiescent Current: IQMAX = 1mA
- Compatible with Low ESR Ceramic Capacitor
- Operation Junction Temperature: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

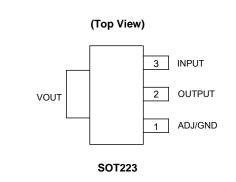
Typical Applications Circuit (Note 4)



Note 4: The AZ2117 is compatible with low ESR ceramic capacitor. The ESR of the output capacitors must be less than 20Ω . A minimum of 1µF output capacitor is required.

LOW DROPOUT LINEAR REGULATOR

Pin Assignments

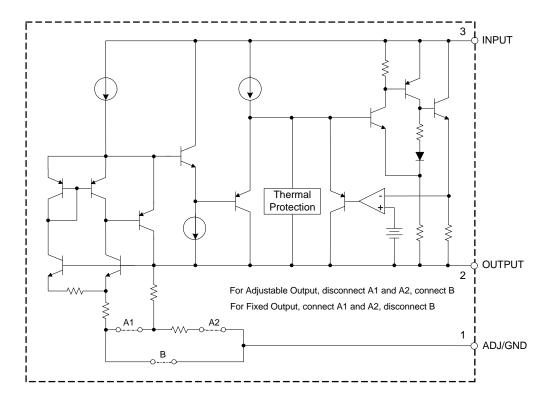


Applications

- USB Device
- Add-on Card
- DVD Player
- PC Motherboard



Functional Block Diagram



Absolute Maximum Ratings (Note 5)

Symbol	Parameter	Rat	Rating		
V _{IN}	Input Voltage	18	18		
TJ	Operating Junction Temperature Range	+1	+150		
T _{STG}	Storage Temperature Range	-65 to	-65 to +150		
θ _{JA}	Thermal Resistance (Without Heatsink)	SOT223	125	°C/W	
θ _{JA}	Thermal Resistance (With Heatsink) (Note 6)	SOT223	SOT223 100		
T _{LEAD}	Lead Temperature (Soldering, 10sec)	+20	+260		

Notes: 5. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

6. Chip is soldered to 100mm²(10mm*10mm) copper (top side solder mask) on 2oz.2 layers FR-4 PCB with 8*0.5mm vias.

Recommended Operating Conditions

Symbol	Parameter	Min	Мах	Unit
V _{IN}	Input Voltage		15	V
TJ	Operating Junction Temperature Range	-40	+125	°C



Electrical Characteristics

(Operating Conditions: $V_{IN} \le 10V$, $I_{OUT} = 10mA$, $T_J = +25$ °C, unless otherwise specified. (P \le maximum power dissipation). Limits appearing in **Boldface** type apply over the entire junction temperature range for operation, -40°C to +125°C.)

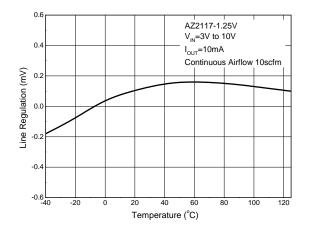
Symbol	Parameter	Conditions		Min	Тур	Max	Unit		
N/		V _{OUT} +1.75V ≤ V _{IN} ≤ 12V,		1.238	1.250	1.262	V		
V _{REF} Reference Voltage		I _{OUT} = 10mA		98%*V _{OUT}	V _{OUT}	102%*V _{ОUT}	V		
Vdrop	Dropout Voltage	I _{OUT} = 1A		I _{OUT} = 1A		_	1.3	1.5	V
I _{LIMIT} (Note 7)	Maximum Output Current	1.75V ≤ V _{IN} -V _{OUT}		1.25	1.35	1.5	А		
V _{RLOAD}	Load Regulation	$V_{IN} = V_{OUT}$ +1.75V 1mA ≤ I _{OUT} ≤ 1A		_	0.2	0.6	%/A		
V _{RLINE}	Line Regulation	$1.75V \le V_{IN}-V_{OUT} \le 10V,$ $I_{OUT} = 30mA$		—	0.001	0.04	%/V		
Ι _Q	Quiescent Current	$I_{OUT} = 0$		_	0.35	1	mA		
_	Minimum Load Current	For ADJ Version, 1.75V ≤ V _{IN} -V _{OUT} ≤ 10V		—	0.3	1	mA		
I _{ADJ}	Adjustable Pin Current	_		_	7	10	μA		
_	Adjustable Pin Current Change	1.75V ≤ V _{IN} -V _{OUT} ≤ 10V		—	0.3	2	μA		
	Power Supply Rejection Ratio	Ripple 1.0 Vp-p $V_{IN} = V_{OUT}+2V$, $I_{OUT} = 100$ mA	f = 120Hz	_	60	_	dB		
PSRR			f = 1kHz	_	60	_			
$\frac{\Delta V_{OUT} / V_{OUT}}{\Delta T}$	Output Voltage Temperature Coefficient	I _{OUT} = 30mA		_	±100	_	ppm/ °C		
VNOISE	RMS Output Noise	$10Hz \le f \le 100kHz$, No Load		_	0.003	_	%		
T _{OTSD}	Thermal Shutdown Temperature	-		—	+170	_	°C		
T _{HYOTSD}	Thermal Shutdown Hysteresis	-		_	+20	_	°C		
θ _{JC}	Thermal Resistance (Junction to Case)	SOT223		_	40	_	°C/W		

Note 7: Make the V_{OUT} down to about 98% of the test values, I_{OUT} value is set to I_{LIMIT} at this time.

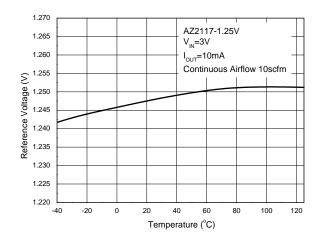


Performance Characteristics

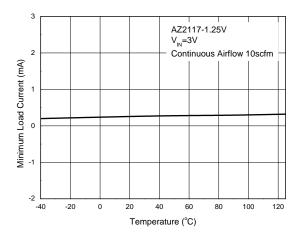
Line Regulation vs. Temperature



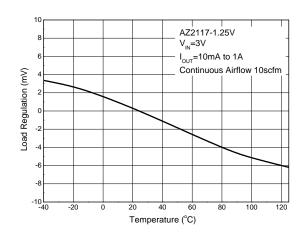
Reference Voltage vs. Temperature



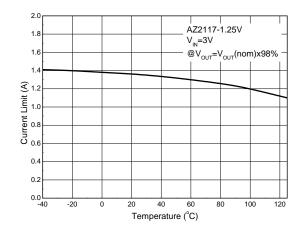
Minimum Load Current vs. Temperature



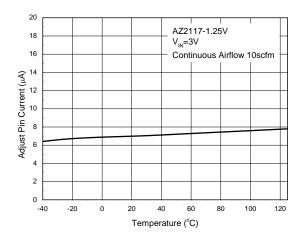
Load Regulation vs. Temperature



Current Limit vs. Temperature



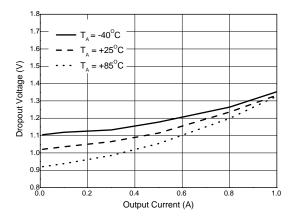
Adjust Pin Current vs. Temperature



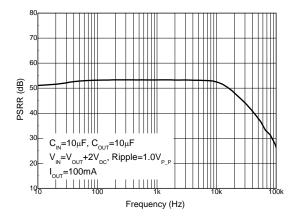


Performance Characteristics (Cont.)

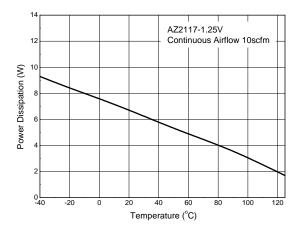
Dropout Voltage vs. Output Current



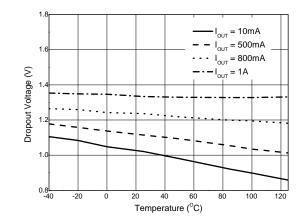
PSRR vs. Frequency



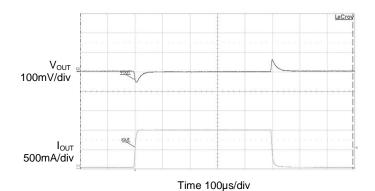
Power Dissipation vs. Temperature



Dropout Voltage vs. Temperature



Load Transient Response

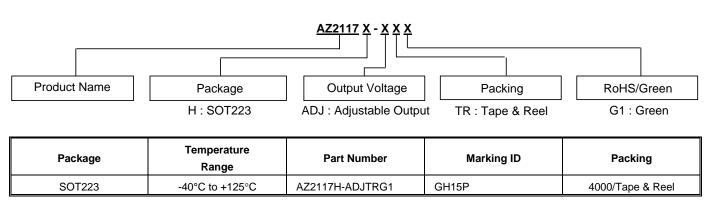


NEW PRODUCT

AZ2117



Ordering Information



Marking Information

(1) SOT223

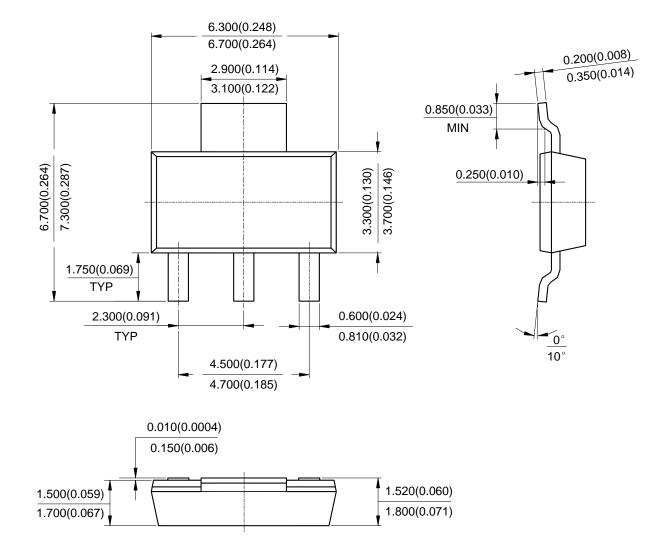


First Line: Logo and Marking ID (See Ordering Information) Second Line: Date Code Y: Year WW: Work Week of Molding A: Assembly House Code XX: 7th and 8th Digits of Batch Number



Package Outline Dimensions (All dimensions in mm (inch).)

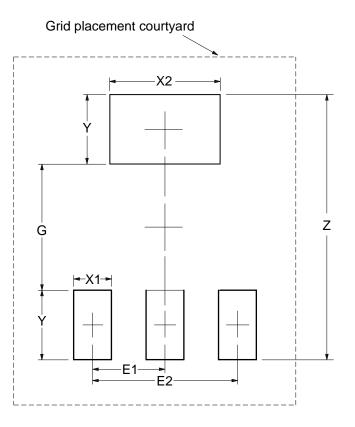
(1) Package Type: SOT223





Suggested Pad Layout

(1) Package Type: SOT223



Dimensions	Z	G	X1	X2	Y	E1	E2
	(mm)/(inch)						
Value	8.400/0.331	4.000/0.157	1.200/0.047	3.500/0.138	2.200/0.087	2.300/0.091	4.600/0.181



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